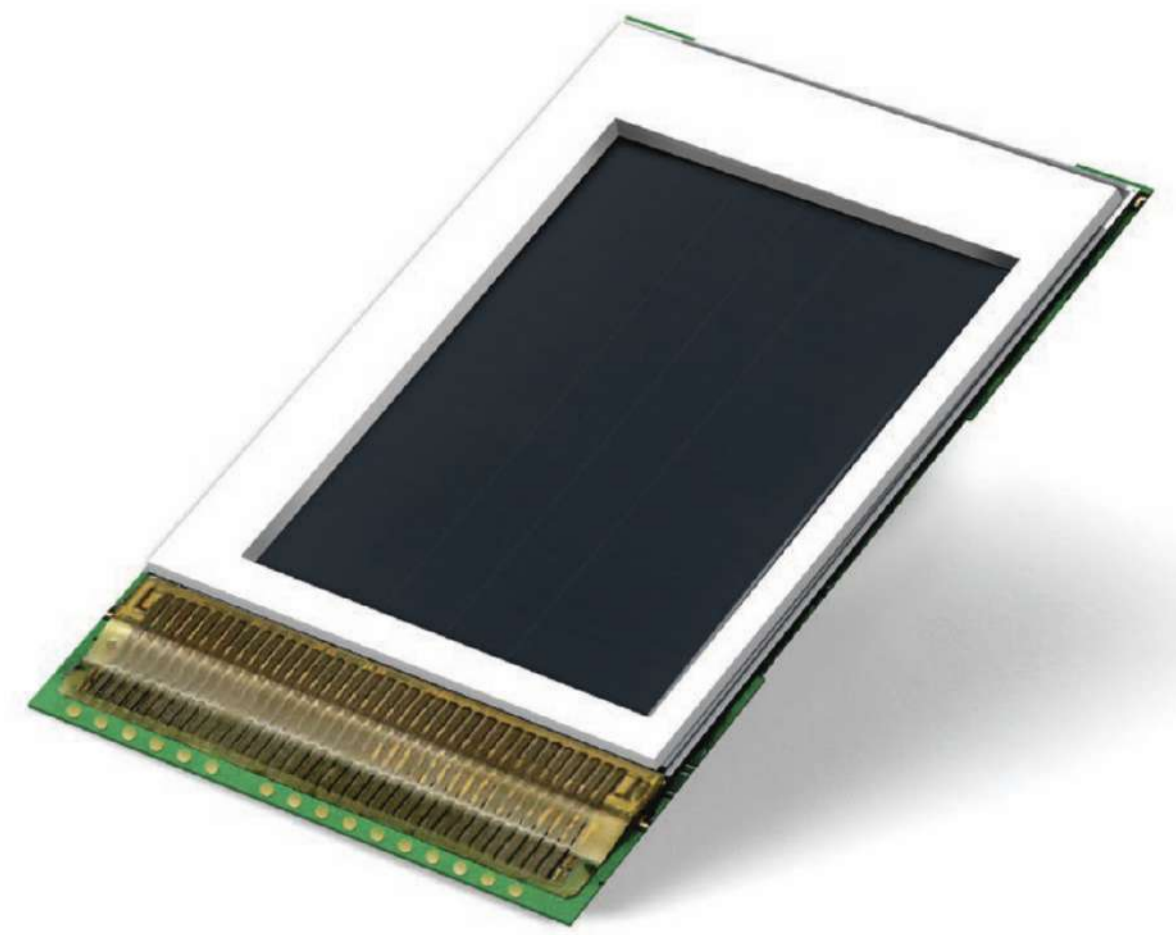


NEXT BIOMETRICS NB-65210-S



Reliable protection of assets and intellectual property starts right on an organization`s doorsteps and extends to logical access to networks and devices. Fingerprint-based access control solutions contribute to an encompassing security concept by offering a secure, fast, efficient and user-friendly means to manage security.

The NEXT Biometrics NB-65210-S takes NEXT Biometrics' range of highly accurate and convenient fingerprint sensor solutions to an even higher level of security. Based on the FAP20 fingerprint sensor, the thinnest sensor of its kind, this high-performance fingerprint module is ideally suited for integration into a broad range of applications and devices.

Building on the patented and proven NEXT Active Thermal® principle, The NEXT Biometrics NB-65210-S fingerprint module offers excellent image quality and constant accurate performance, thus producing fewer false acceptance and false rejection rates than other available solutions and resulting in an excellent user experience. The module meets FBI image quality standards and complies with PIV requirements specified by PIV-071006.

The large-area, 500dpi resolution sensor reliably copes with real-life complexities like skewed finger placement, as well as damaged, dirty, dry or wet fingers to provide high quality fingerprints. Automatic finger detection enables a quick scan when the finger is placed on the sensor. Equipped with a smart scan sequence, the sensor allows for capture of any custom image size.

The NEXT Biometrics NB-65210-S offers a high level of security. Based on its anti-spoofing ability, it reliably rejects latent fingerprint images and prevents against fake finger attacks.

NEXT Biometrics offers SDK support with one touch enrollment, 360-degree rotational tolerance and biometric performance of <1% FRR @0.01% FAR. The templates generated meet ISO/IEC19794-2:2011 for easy and seamless integration into a broad range of devices and end-user applications.

DESIGNED FOR INTEGRATION INTO

- Readers & peripherals
- Terminals & kiosks
- Notebooks, Tablets, PDAs and Handheld devices

SUITABLE FOR APPLICATIONS LIKE

- Physical access control
- Network and device security
- Banking, financial systems and mobile operators (eKYC)
- Healthcare and medical information systems
- Time & Attendance
- Visitor identification & management



ACTIVE SENSING AREA (MM):
15.24 × 20.32



www.nextbiometrics.com

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FEATURES

- Automatic Finger Detection
- Anti-Latent Rejection
- Anti-Spoof & Fake Finger Detection
- Smart configurable scan mode supporting custom scan size

NEXT BIOMETRICS SDK FEATURES

- ISO/IEC 19794-2 template format
- Complete rotational tolerance (360 degree)
- < 1% FRR @0.01% FAR
- One touch enrollment & verification
- Supports Windows 10/8.1/8/7, Android, Linux

TECHNICAL SPECIFICATIONS

| | |
|-----------------------------|---|
| Product Name | One Touch ID 2010 |
| Module Ordering Number | NB-65210-S-101 |
| Sensor Technology | NEXT Active Thermal® sensing (patented) |
| Specification | FBI PIV & Mobile ID FAP20 |
| Module size (mm) | 22 × 35 × 3.0 |
| Active sensing area (mm) | 15.24 × 20.32 |
| Image size | 300 × 400 pixels |
| Image resolution | 500 ppi |
| Image gray scale levels | 256 |
| Image Quality | PIV (PIV-071006) |
| Logical interface | SPI |
| Physical interface | 12-pin FPC connector |
| Power supply | 3.3 V |
| Scan time | 0.76 seconds |
| Scan current | Typical 60 mA |
| Standby current consumption | 200 µA |
| Scratch resistance | DLC coating providing 20N @ 9H per ASTM D3363-00 |
| ESD protection | ±8 kV contact discharge, ±15 kV air discharge per IEC 61000-4-2 |
| Dust/Water resistance | Enables IP67 protection according to IEC 60529 |
| Operating conditions | -20°C to +60°C at 90% RH (non-condensing) |
| Storage conditions | -30°C to +70°C at 90% RH (non-condensing) |

